

[Products](#)
[INTEL Cooler](#)
[AMD Cooler](#)
[DC-FAN](#)
[FB DIMM Heat](#)
[NB-Thermal](#)
[LED-Thermal](#)
[Cable](#)

 You are here: [Home](#) > [Products](#) > [INTEL Cooler](#) > [INTEL LGA775 ATX Solution](#)

INTEL LGA775 ATX Solution


Z9U741L001

Patent heatpipe penetrate 62 pieces of Fin arranged densely and equably to make heat emitted immediately; Special FAN Cover design and the round big FAN can coc down the electric organs on the motherboard around it



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Heat Sink Profile	
Heat Sink Dim	110W*100H*73L
Material of Fins	AL 1050
Fin Dim	0.3t*95W*43L*43Fins
Material of Base	Cu 1100
Copper Base Dim	O35*39L
Heat Pipe	O6*4 pcs Groove Type
Tim	ShinEtsu 7762
Fan Profile	
P/N of fan:	DA09025T12UP011
Fan Speed:	4400RPM
Fan Speed on Cooler:	85.4 CFM (Free Air)
Max.Air Flow:	10.02 mmH2O(Free Air)
Max.Air Pressure;	10.1mmH2O
Total Weight:430g(with fan)	
Thermal Resistance:0.192 C/W by SMF TTV	